

**Amendments to the Specification:**

Please rewrite the paragraph beginning at page 8, line 4, with the following rewritten paragraph:

B1  
--According to one embodiment of such a heat sink, the body is formed from a metal (either ~~form~~ from sheet or by extrusion) to provide heat dissipating fins in substantially parallel planes, and support elements extending away from the planes to provide surface mounting lands remote from the major surface areas of said fins, and thermally conductive solderable surface mounting elements are aligned with and mechanically attached to the lands.--

Please replace the paragraph beginning at page 10, line 12, with the following rewritten paragraph:

B2  
--The respective solderable element(s) may be provided ~~thereof upon~~ on a surface of the support element and ~~fastening therebetween~~ fastened thereto by use of a rivet or ~~the like~~ other surface-penetrating fastener.--

Please replace the paragraph beginning at page 12, line 2, with the following rewritten paragraph:

B3  
--Fig. 1(a) 1A is a perspective view of a heat sink adapted for surface mounting;--

Please replace the paragraph beginning at page 12, line 3, with the following rewritten paragraph:

B4  
--Fig. 1(b) 1B is a part-sectional view of a part of the heat sink shown in Fig. 1, and illustrating schematically the structural parts for achieving a mechanical interfit in the assembly;--

Please replace the paragraph beginning at page 12, line 6, with the following rewritten paragraph:

B5 --Fig. 2 Figs. 2A-2C illustrate schematically, in three stages, a typical "re-flow" process for attaching components to a prepared surface;--

Please replace the paragraph beginning at page 13, line 3, with the following rewritten paragraph:

B6 --A surface mounted heat sink assembly according to one aspect of the present invention is illustrated in Figure 1 1A. An anodized blackened, aluminum sheet is formed to provide a finned heat sink 1 having freely extending heat dissipating fins 2 arranged on either side of a planar section 3 intended to be arranged in use over an electronic device (not shown) to be protected against heat overload. The heat sink 1 has surface mounting lands 4 at the base of the heat sink which are adapted for soldering to a substrate by a soldering technique known *per se* in the field, e.g. solder reflow methods, by the provision of thermally conductive solderable elements 5. These solderable elements 5 are contiguous with and extend over the surface of the lands 4, and are retained in position by a mechanical fixing (~~Fig. 1(b)~~). ~~Such.~~ Referring to Figure 1B, such a mechanical fixing is achievable by partially shearing or semi-perforating the land to drive out a projection to provide a spigot 6 (~~Fig. 1b~~) that is inserted into a corresponding socket 7 formed in the solderable element 5, and that interference fit is enhanced by swaging the element 5 onto the land 4. It will be appreciated that the swaging operation is best carried out before the sheet is formed into the desired finned profile of the heat sink body shown in Fig. 1 1A.--

Please replace the paragraph beginning at page 14, line 8, with the following rewritten paragraph:

---

B7 --In use of the embodiment shown in Fig. 1 1A, the heat sink is oriented to present the lands for surface mounting and on either side of a device to be protected against heat overload, such that the planar surface 3 is positioned over the device (not shown).--

---

Please replace the paragraph beginning at page 14, line 11, with the following rewritten paragraph:

---

BS --As is known in the field, the heat sink dissipates heat by a combination of conduction of heat by contact with hot surfaces e.g. the regions of contact between the lands 4 and the elements 5 in the surface mounting arrangement with the respective areas of substrate (not shown in Fig. 1 1A), and by convection through ambient air currents, and radiation from the heat sink body.--

---